



Product/Process Change Notice - PCN 20_0353 Rev. -

Analog Devices, Inc. Three Technology Way Norwood, Massachusetts 02062-9106

This notice is to inform you of a change that will be made to certain ADI products (see Appendix A) that you may have purchased in the last 2 years. **Any inquiries or requests with this PCN (additional data or samples) must be sent to ADI within 30 days of publication date.** ADI contact information is listed below.

PCN Title: Assembly Site Transfer of Select LFCSP Products to ASE Korea

Publication Date: 04-Dec-2020

Effectivity Date: 08-Mar-2021 *(the earliest date that a customer could expect to receive changed material)*

Revision Description:

Initial Release.

Description Of Change:

Assembly site is transferring from Amkor, Philippines to ASE, Korea for select LFCSP products.

ADI will qualify AD9152 product using ASE Korea's Bill of Materials (BOM).

The package outline dimensions, mold compound, die attach and wire diameter of this product will be maintained.

Reason For Change:

Amkor Technology has issued an end-of-life notification for the leadframes being supplied by Advance Leadframe Solution. ASE Korea is being utilized as an assembly site to ensure an additional source of supply for LFCSP products.

ADI's assembly subcontractors manufacture products using Analog Devices specified manufacturing flows, materials, process controls and monitors, ensuring the same level of quality and reliability on products they receive from the new site.

Impact of the change (positive or negative) on fit, form, function & reliability:

The change will have no impact on fit, form, function and reliability of the devices.

Product Identification *(this section will describe how to identify the changed material)*

Assembled parts will be identified by assembly lot number.

Summary of Supporting Information:

Qualification will be performed per Industry Standard Test Methods. See attached Qualification Plan.

Supporting Documents

Attachment 1: Type: Qualification Plan

ADI_PCN_20_0353_Rev_-_Qualification_Plan_Summary.pdf

For questions on this PCN, please send an email to the regional contacts below or contact your local ADI sales representatives.

Americas:
PCN_Americas@analog.com

Europe:
PCN_Europe@analog.com

Japan:
PCN_Japan@analog.com

Rest of Asia:
PCN_ROA@analog.com

Appendix A - Affected ADI Models

Added Parts On This Revision - Product Family / Model Number (2)

AD9152 / AD9152BCPZ

AD9152 / AD9152BCPZRL

Appendix B - Revision History

Rev	Publish Date	Effectivity Date	Rev Description
Rev. -	04-Dec-2020	08-Mar-2021	Initial Release.

Analog Devices, Inc.

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Qualification Plan Summary for 8x8 Sawn LFCSP at ASE Korea

TEST	SPECIFICATION	SAMPLE SIZE	EXPECTED COMPLETION DATE
Temperature Cycle (TC)*	JEDEC <i>JESD22-A104</i>	3 x 32	Mar 2021
Solder Heat Resistance (SHR)*	JEDEC/IPC <i>J-STD-020</i>	3 x 11	Mar 2021
Highly Accelerated Stress Test (HAST)*	JEDEC <i>JESD22-A110</i>	9 x 32	Pass
High Temperature Storage (HTS)	JEDEC <i>JESD22-A103</i>	1 x 32	Mar 2021
Unbiased Highly Accelerated Stress Test (UHAST)*	JEDEC <i>JESD22-A102</i>	3 x 32	Mar 2021

* Preconditioned per JEDEC/IPC J-STD-020.